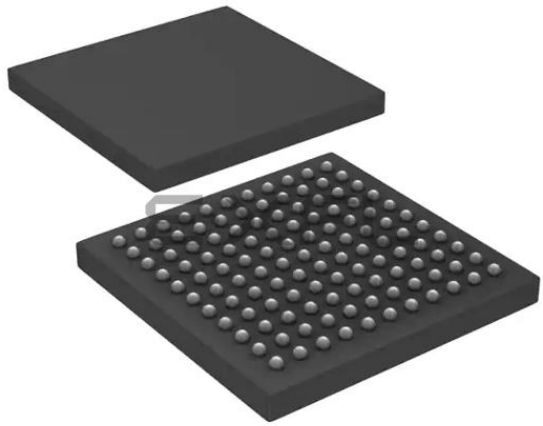
Microchip Technology - PIC32MX460F512LT-80I/BG Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	-
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx460f512lt-80i-bg

Pin Diagrams (Continued)

100-Pin TQFP (General Purpose)

= Pins are up to 5V tolerant

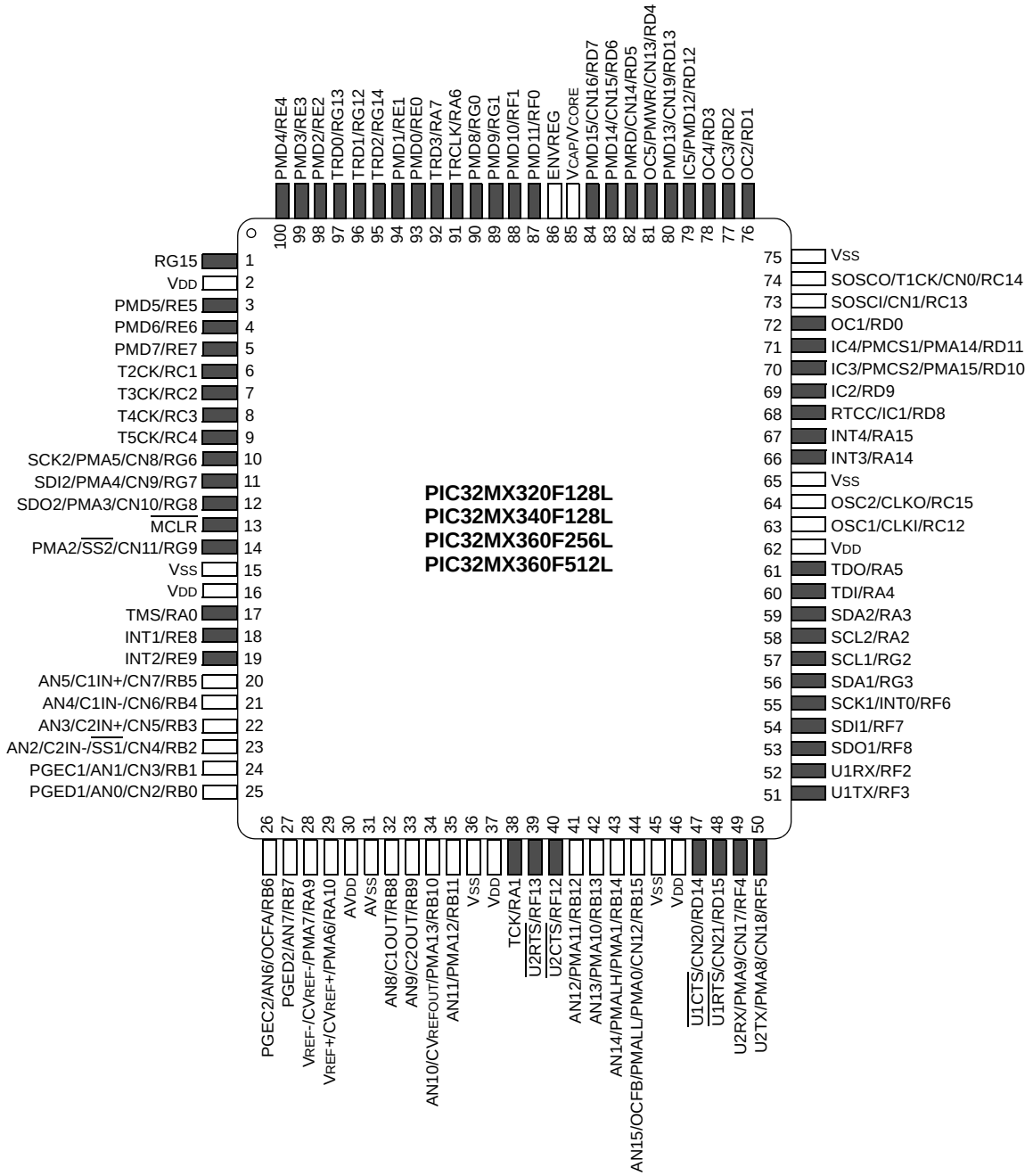


TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
PGED2	18	27	J3	I/O	ST	Data I/O pin for programming/debugging communication channel 2.
PGEC2	17	26	L1	I	ST	Clock input pin for programming/debugging communication channel 2.
$\overline{MCLR}$	7	13	F1	I/P	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	19	30	J4	P	P	Positive supply for analog modules. This pin must be connected at all times.
AVSS	20	31	L3	P	P	Ground reference for analog modules.
VDD	10, 26, 38	2, 16, 37, 46, 62	C2, C9, E5, F8, G5, H4, H6, K8	P	—	Positive supply for peripheral logic and I/O pins.
VCORE/ VCAP	56	85	B7	P	—	Capacitor for Internal Voltage Regulator.
Vss	9, 25, 41	15, 36, 45, 65, 75	A8, B10, D4, D5, E7, F10, F5, G6, G7, H3	P	—	Ground reference for logic and I/O pins.
VREF+	16	29	K3	I	Analog	Analog voltage reference (high) input.
VREF-	15	28	L2	I	Analog	Analog voltage reference (low) input.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

3.2 Architecture Overview

The MIPS32® M4K® Processor Core contains several logic blocks working together in parallel, providing an efficient high performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32® M4K® Processor Core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit general purpose registers used for integer operations and address calculation. One additional register file shadow set (containing thirty-two registers) is added to minimize context switching overhead during interrupt/exception processing. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instructions streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and Store Aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32® M4K® Processor Core includes a multiply/divide unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the integer unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the *rs* operand. The second number ('16' of 32x16) represents the *rt* operand. The PIC32MX core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If rs is 8 bits wide, 23 iterations are skipped. For a 16-bit-wide rs, 15 iterations are skipped, and for a 24-bit-wide rs, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32MX core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
MULT/MULTU, MADD/MADDU, MSUB/MSUBU	16 bits	1	1
	32 bits	2	2
MUL	16 bits	2	1
	32 bits	3	2
DIV/DIVU	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

The MIPS architecture defines that the result of a multiply or divide operation be placed in the HI and LO registers. Using the Move-From-HI (MFHI) and Move-From-LO (MFLO) instructions, these values can be transferred to the general purpose register file.

In addition to the HI/LO targeted operations, the MIPS32 architecture also defines a multiply instruction, MUL, which places the least significant results in the primary register file instead of the HI/LO register pair. By avoiding the explicit MFLO instruction, required when using the LO register, and by supporting multiple destination registers, the throughput of multiply-intensive operations is increased.

Two other instructions, multiply-add (MADD) and multiply-subtract (MSUB), are used to perform the multiply-accumulate and multiply-subtract operations. The MADD instruction multiplies two numbers and then adds the product to the current contents of the HI and LO registers. Similarly, the MSUB instruction multiplies two operands and then subtracts the product from the HI and LO registers. The MADD and MSUB operations are commonly used in DSP algorithms.

3.2.3 SYSTEM CONTROL COPROCESSOR (CP0)

In the MIPS architecture, CP0 is responsible for the virtual-to-physical address translation, the exception control system, the processor's diagnostics capability, the operating modes (kernel, user and debug), and whether interrupts are enabled or disabled. Configuration information, such as presence of options like MIPS16e, is also available by accessing the CP0 registers, listed in Table 3-2.

TABLE 3-2: COPROCESSOR 0 REGISTERS

Register Number	Register Name	Function
0-6	Reserved	Reserved
7	HWREna	Enables access via the RDHWR instruction to selected hardware registers
8	BadVAddr(1)	Reports the address for the most recent address-related exception
9	Count(1)	Processor cycle count
10	Reserved	Reserved
11	Compare(1)	Timer interrupt control
12	Status(1)	Processor status and control
12	IntCtl(1)	Interrupt system status and control
12	SRSCtl(1)	Shadow register set status and control
12	SRSMap(1)	Provides mapping from vectored interrupt to a shadow set
13	Cause(1)	Cause of last general exception
14	EPC(1)	Program counter at last exception
15	PRId	Processor identification and revision
15	EBASE	Exception vector base register
16	Config	Configuration register
16	Config1	Configuration register 1
16	Config2	Configuration register 2
16	Config3	Configuration register 3

4.0 MEMORY ORGANIZATION

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 3. "Memory Organization"** (DS61115) of the *"PIC32 Family Reference Manual",* which is available from the Microchip web site (www.microchip.com/PIC32).

PIC32MX3XX/4XX microcontrollers provide 4 GB of unified virtual memory address space. All memory regions including program, data memory, SFRs and Configuration registers reside in this address space at their respective unique addresses. The program and data memories can be optionally partitioned into user and kernel memories. In addition, the data memory can be made executable, allowing PIC32MX3XX/4XX to execute from data memory.

4.1 Key Features

- 32-bit native data width
- Separate User and Kernel mode address space
- Flexible program Flash memory partitioning
- Flexible data RAM partitioning for data and program space
- Separate boot Flash memory for protected code
- Robust bus exception handling to intercept runaway code
- Simple memory mapping with Fixed Mapping Translation (FMT) unit
- Cacheable and non-cacheable address regions

4.2 PIC32MX3XX/4XX Memory Layout

PIC32MX3XX/4XX microcontrollers implement two address spaces: Virtual and Physical. All hardware resources such as program memory, data memory and peripherals are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions as well as access peripherals. Physical addresses are used by peripherals such as DMA and Flash controller that access memory independently of CPU.

TABLE 4-12: SPI1-2 REGISTERS MAP(1,2)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5800	SPI1CON	31:16	FRMEN	FRMSYNC	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	SPIFE	—	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	—	—	—	—	—	0000
5810	SPI1STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	SPIBUSY	—	—	—	—	SPIROV	—	—	SPITBE	—	—	SPIRBF	0008
5820	SPI1BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5830	SPI1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	BRG<8:0>									0000
5A00	SPI2CON	31:16	FRMEN	FRMSYNC	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	SPIFE	—	0008
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	—	—	—	—	—	0000
5A10	SPI2STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	SPIBUSY	—	—	—	—	SPIROV	—	—	SPITBE	—	—	SPIRBF	0008
5A20	SPI2BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5A30	SPI2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	BRG<8:0>									0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table except SPIxBUF have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: SPI2 Module is not present on PIC32MX420FXXXX/440FXXXX devices.

TABLE 4-39: PREFETCH REGISTERS MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
4000	CHECON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CHECOH	0000
		15:0	—	—	—	—	—	—	DCSZ<1:0>		—	—	PREFEN<1:0>		—	PFMWS<2:0>			0007
4010	CHEACC(1)	31:16	CHEWEN	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	CHEIDX<3:0>				00xx
4020	CHETAG(1)	31:16	LTAGBOOT	—	—	—	—	—	—	—	LTAG<23:16>								xxx0
		15:0	LTAG<15:4>												LVALID	LLOCK	LTYPE	—	xxx2
4030	CHEMSK(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LMASK<15:5>											—	—	—	—	—	xxxx
4040	CHEW0	31:16	CHEW0<31:0>																xxxx
		15:0																	xxxx
4050	CHEW1	31:16	CHEW1<31:0>																xxxx
		15:0																	xxxx
4060	CHEW2	31:16	CHEW2<31:0>																xxxx
		15:0																	xxxx
4070	CHEW3	31:16	CHEW3<31:0>																xxxx
		15:0																	xxxx
4080	CHELRU	31:16	—	—	—	—	—	—	—	CHELRU<24:16>									0000
		15:0	CHELRU<15:0>																0000
4090	CHEHIT	31:16	CHEHIT<31:0>																xxxx
		15:0																	xxxx
40A0	CHEMIS	31:16	CHEMIS<31:0>																xxxx
		15:0																	xxxx
40C0	CHEPFABT	31:16	CHEPFABT<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

8.0 OSCILLATOR CONFIGURATION

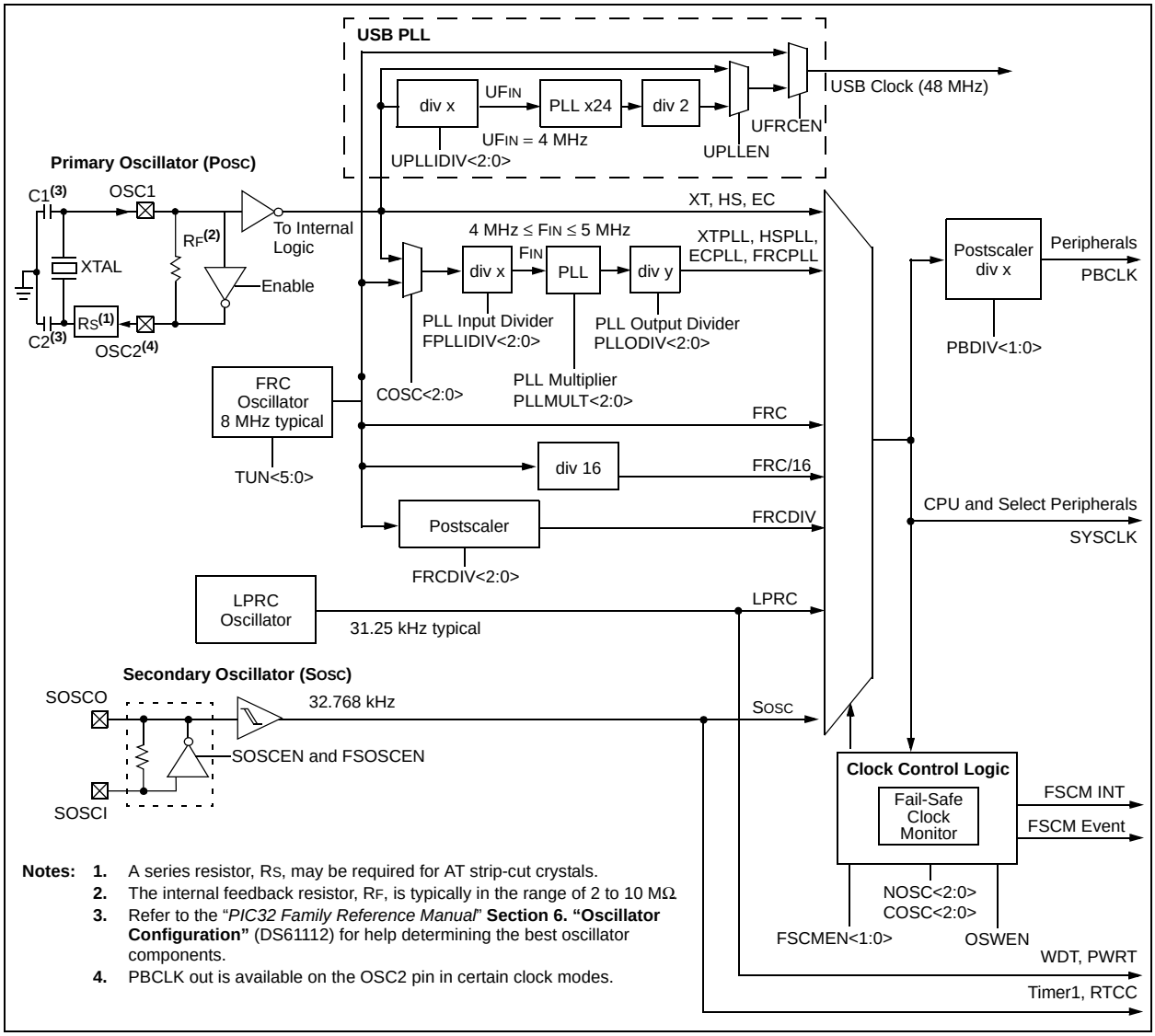
Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC32 Family Reference Manual"* **Section 6. "Oscillator Configuration"** (DS61112), which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC32MX oscillator system has the following modules and features:

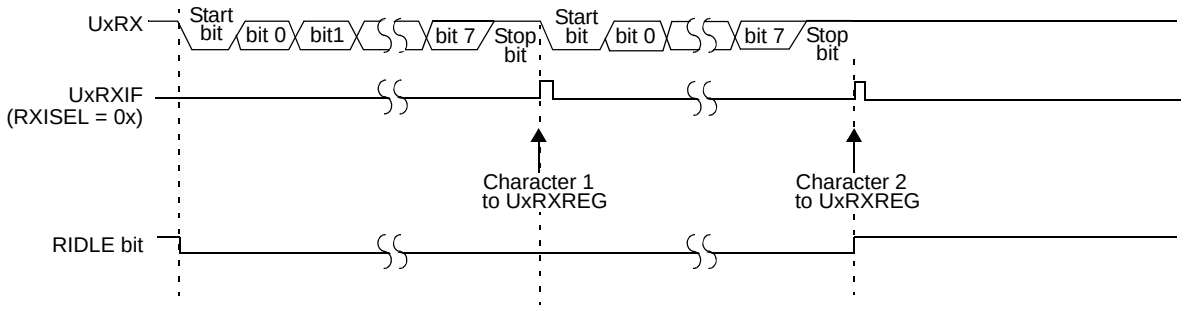
- A total of four external and internal oscillator options as clock sources
- On-chip PLL (phase-locked loop) with user-selectable input divider, multiplier and output divider to boost operating frequency on select internal and external oscillator sources
- On-chip user-selectable divisor postscaler on select oscillator sources
- Software-controllable switching between various clock sources
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shut down
- Dedicated on-chip PLL for USB peripheral

FIGURE 8-1: PIC32MX3XX/4XX FAMILY CLOCK DIAGRAM



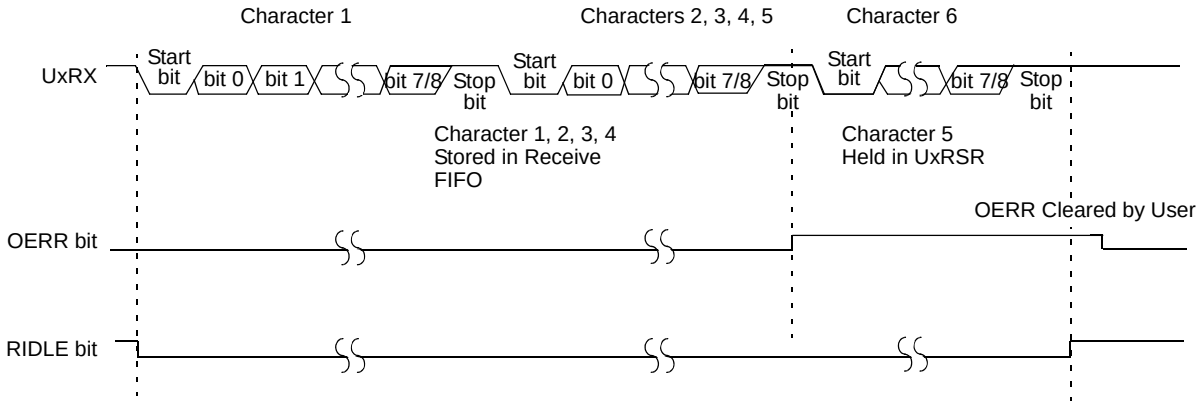
Notes:
1. A series resistor, RS, may be required for AT strip-cut crystals.
2. The internal feedback resistor, RF, is typically in the range of 2 to 10 MΩ
3. Refer to the "*PIC32 Family Reference Manual*" **Section 6. "Oscillator Configuration"** (DS61112) for help determining the best oscillator components.
4. PBCLK out is available on the OSC2 pin in certain clock modes.

FIGURE 19-4: UART RECEPTION



Note: This timing diagram shows 2 characters received on the UxRX input.

FIGURE 19-5: UART RECEPTION WITH RECEIVE OVERRUN



Note: This diagram shows 6 characters received without the user reading the input buffer. The 5th character received is held in the Receive Shift register. An overrun error occurs at the start of the 6th character.

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS61125) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC32MX RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

The following are some of the key features of this module:

- Time: Hours, Minutes and Seconds
- 24-Hour Format (Military Time)
- Visibility of One-Half-Second Period
- Provides Calendar: Weekday, Date, Month and Year
- Alarm Intervals are configurable for Half of a Second, One Second, 10 Seconds, One Minute, 10 Minutes, One Hour, One Day, One Week, One Month and One Year
- Alarm Repeat with Decrementing Counter
- Alarm with Indefinite Repeat: Chime
- Year Range: 2000 to 2099
- Leap Year Correction
- BCD Format for Smaller Firmware Overhead
- Optimized for Long-Term Battery Operation
- Fractional Second Synchronization
- User Calibration of the Clock Crystal Frequency with Auto-Adjust
- Calibration Range: ±0.66 Seconds Error per Month
- Calibrates up to 260 ppm of Crystal Error
- Requirements: External 32.768 kHz Clock Crystal
- Alarm Pulse or Seconds Clock Output on RTCC pin

FIGURE 21-1: RTCC BLOCK DIAGRAM

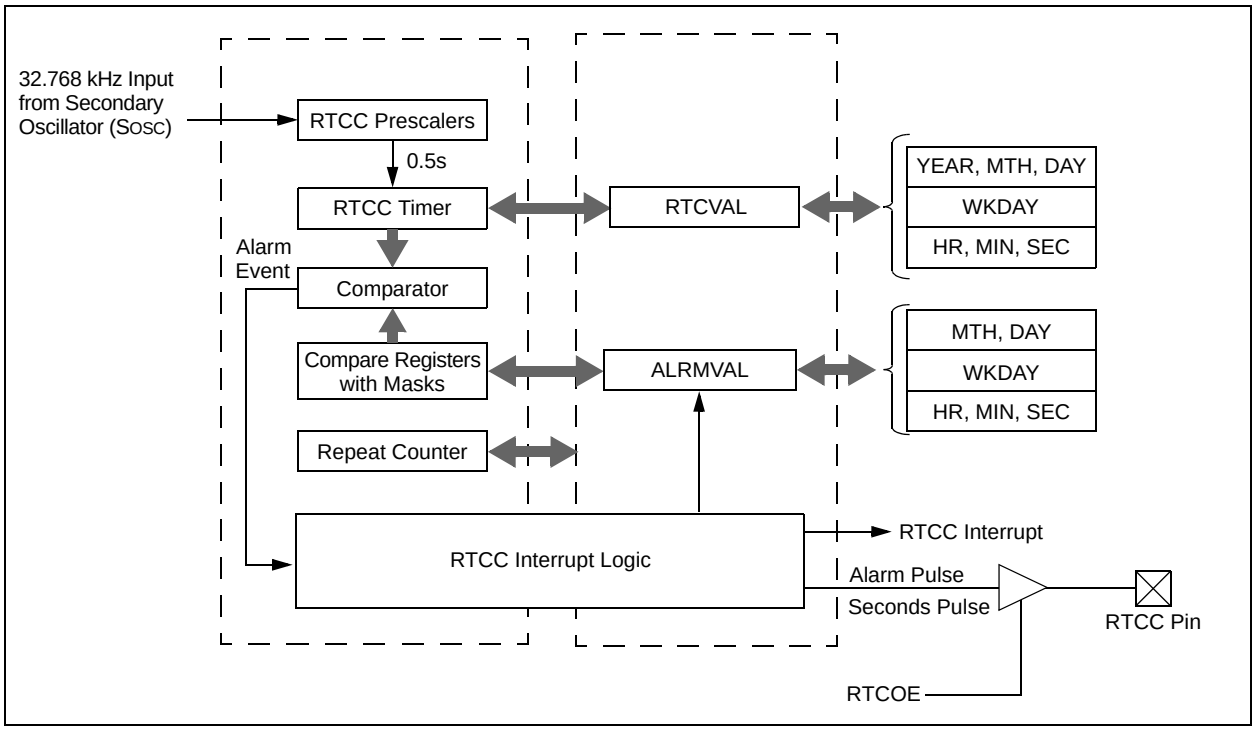


TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function

BLEZL	Branch on Less Than or Equal to Zero Likely(1)	if Rs[31] || Rs == 0
		  PC += (int)offset
		else
		  Ignore Next Instruction

BLTZ	Branch on Less Than Zero	if Rs[31] PC += (int)offset
BLTZAL	Branch on Less Than Zero and Link	GPR[31] = PC + 8 if Rs[31] PC += (int)offset

BLTZALL	Branch on Less Than Zero and Link Likely(1)	GPR[31] = PC + 8
		if Rs[31]
		  PC += (int)offset
		else
		  Ignore Next Instruction

BLTZL	Branch on Less Than Zero Likely(1)	if Rs[31]
		  PC += (int)offset
		else
		  Ignore Next Instruction

BNE	Branch on Not Equal	if Rs != Rt PC += (int)offset

BNEL	Branch on Not Equal Likely(1)	if Rs != Rt
		  PC += (int)offset
		else
		  Ignore Next Instruction

BREAK	Breakpoint	Break Exception
CLO	Count Leading Ones	Rd = NumLeadingOnes(Rs)
CLZ	Count Leading Zeroes	Rd = NumLeadingZeroes(Rs)
DERET	Return from Debug Exception	PC = DEPC Exit Debug Mode
DI	Atomically Disable Interrupts	Rt = Status; $Status_{IE}$ = 0
DIV	Divide	LO = (int)Rs / (int)Rt HI = (int)Rs % (int)Rt
DIVU	Unsigned Divide	LO = (uns)Rs / (uns)Rt HI = (uns)Rs % (uns)Rt
EHB	Execution Hazard Barrier	Stop instruction execution until execution hazards are cleared
EI	Atomically Enable Interrupts	Rt = Status; $Status_{IE}$ = 1

ERET	Return from Exception	if $Status_{ERL}$
		  PC = ErrorEPC
		else
		  PC = EPC
		  $Status_{EXL}$ = 0
		$Status_{ERL}$ = 0
		LL = 0

EXT	Extract Bit Field	Rt = ExtractField(Rs, pos, size)
INS	Insert Bit Field	Rt = InsertField(Rs, Rt, pos, size)
J	Unconditional Jump	PC = PC[31:28] || offset<<2

Note 1: This instruction is deprecated and should not be used.

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
JAL	Jump and Link	GPR[31] = PC + 8 PC = PC[31:28] || offset<<2
JALR	Jump and Link Register	Rd = PC + 8 PC = Rs
JALR.HB	Jump and Link Register with Hazard Barrier	Like JALR, but also clears execution and instruction hazards
JR	Jump Register	PC = Rs
JR.HB	Jump Register with Hazard Barrier	Like JR, but also clears execution and instruction hazards
LB	Load Byte	Rt = (byte)Mem[Rs+offset]
LBU	Unsigned Load Byte	Rt = (ubyte))Mem[Rs+offset]
LH	Load Halfword	Rt = (half)Mem[Rs+offset]
LHU	Unsigned Load Halfword	Rt = (uhalf)Mem[Rs+offset]
LL	Load Linked Word	Rt = Mem[Rs+offset> LL_{bit} = 1 LLAdr = Rs + offset
LUI	Load Upper Immediate	Rt = immediate << 16
LW	Load Word	Rt = Mem[Rs+offset]
LWPC	Load Word, PC relative	Rt = Mem[PC+offset]
LWL	Load Word Left	Re = Re MERGE Mem[Rs+offset]
LWR	Load Word Right	Re = Re MERGE Mem[Rs+offset]
MADD	Multiply-Add	HI | LO += (int)Rs * (int)Rt
MADDU	Multiply-Add Unsigned	HI | LO += (uns)Rs * (uns)Rt
MFC0	Move from Coprocessor 0	Rt = CPR[0, Rd, sel]
MFHI	Move from HI	Rd = HI
MFLO	Move from LO	Rd = LO
MOVN	Move Conditional on Not Zero	if Rt ¼ 0 then Rd = Rs
MOVZ	Move Conditional on Zero	if Rt = 0 then Rd = Rs
MSUB	Multiply-Subtract	HI | LO -= (int)Rs * (int)Rt
MSUBU	Multiply-Subtract Unsigned	HI | LO -= (uns)Rs * (uns)Rt
MTC0	Move to Coprocessor 0	CPR[0, n, Sel] = Rt
MTHI	Move to HI	HI = Rs
MTLO	Move to LO	LO = Rs
MUL	Multiply with register write	HI | LO =Unpredictable Rd = ((int)Rs * (int)$Rt)_{31..0}$
MULT	Integer Multiply	HI | LO = (int)Rs * (int)Rd
MULTU	Unsigned Multiply	HI | LO = (uns)Rs * (uns)Rd
NOP	No Operation (Assembler idiom for: SLL r0, r0, r0)	
NOR	Logical NOR	Rd = ~(Rs | Rt)
OR	Logical OR	Rd = Rs | Rt
ORI	Logical OR Immediate	Rt = Rs | Immed
RDHWR	Read Hardware Register (if enabled by $HWRE_{na}$ Register)	Re = HWR[Rd]

Note 1: This instruction is deprecated and should not be used.

TABLE 29-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O pins:					
		with TTL Buffer	VSS	—	0.15 VDD	V	**(Note 4)**
		with Schmitt Trigger Buffer	VSS	—	0.2 VDD	V	**(Note 4)**
DI15		$\overline{MCLR}$	VSS	—	0.2 VDD	V	**(Note 4)**
DI16		OSC1 (XT mode)	VSS	—	0.2 VDD	V	**(Note 4)**
DI17		OSC1 (HS mode)	VSS	—	0.2 VDD	V	**(Note 4)**
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
	VIH	**Input High Voltage**					
DI20		I/O pins:					
		with Analog Functions	0.8 VDD	—	VDD	V	**(Note 4)**
		Digital Only	0.8 VDD	—		V	**(Note 4)**
		with TTL Buffer	0.25VDD + 0.8V	—	5.5	V	**(Note 4)**
		with Schmitt Trigger Buffer	0.8 VDD	—	5.5	V	**(Note 4)**
DI25		$\overline{MCLR}$	0.8 VDD	—	VDD	V	**(Note 4)**
DI26		OSC1 (XT mode)	0.7 VDD	—	VDD	V	**(Note 4)**
DI27		OSC1 (HS mode)	0.7 VDD	—	VDD	V	**(Note 4)**
DI28		SDAx, SCLx	0.7 VDD	—	5.5	V	SMBus disabled **(Note 4)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤VPIN ≤5.5 **(Note 4)**
DI30	ICNPU	**CNxx Pull up Current**	50	250	400	µA	VDD = 3.3V, VPIN = VSS
	IIL	**Input Leakage Current**					**(Note 3)**
DI50		I/O Ports	—	—	±1	µA	VSS ≤VPIN ≤VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	µA	VSS ≤VPIN ≤VDD, Pin at high-impedance
DI55		$\overline{MCLR}$	—	—	±1	µA	VSS ≤VPIN ≤VDD
DI56		OSC1	—	—	±1	µA	VSS ≤VPIN ≤VDD, XT and HS modes

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

TABLE 29-13: COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D300	VIOFF	Input Offset Voltage	—	±7.5	±25	mV	AVDD = VDD, AVSS = VSS
D301	VICM	Input Common Mode Voltage	0	—	VDD	V	AVDD = VDD, AVSS = VSS **(Note 2)**
D302	CMRR	Common Mode Rejection Ratio	55	—	—	dB	Max VICM = (VDD - 1)V **(Note 2)**
D303	TRESP	Response Time	—	150	400	ns	AVDD = VDD, AVSS = VSS **(Notes 1,2)**
D304	ON2OV	Comparator Enabled to Output Valid	—	—	10	µs	Comparator module is configured before setting the comparator ON bit. **(Note 2)**
D305	IVREF	Internal Voltage Reference	0.57	0.6	0.63	V	—

Note 1: Response time measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

2: These parameters are characterized but not tested.

TABLE 29-14: VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D310	VRES	Resolution	VDD/24	—	VDD/32	LSb	—
D311	VRAA	Absolute Accuracy	—	—	1/2	LSb	—
D312	TSET	Settling Time(1)	—	—	10	µs	—

Note 1: Settling time measured while CVRR = 1 and CVR3:CVR0 transitions from '0000' to '1111'. This parameter is characterized, but not tested in manufacturing.

TABLE 29-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D320	VCORE	Regulator Output Voltage	1.62	1.80	1.98	V	—
D321	CEFC	External Filter Capacitor Value	8	10	—	µF	Capacitor must be low series resistance (< 1 Ohm)
D322	TPWRT	Power-up Timer Period	—	64	—	ms	ENVREG = 0

TABLE 29-24: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**		**Min.**	**Max.**	**Units**	**Conditions**	
TB10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15.	N = prescale value (1, 2, 4, 8, 16, 32, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15.	
TB15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of 25 ns or 2 TPB)/N] + 30 ns	—	ns	VDD > 2.7V	
				[(Greater of 25 ns or 2 TPB)/N] + 50 ns	—	ns	VDD < 2.7V	—
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	TPB	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

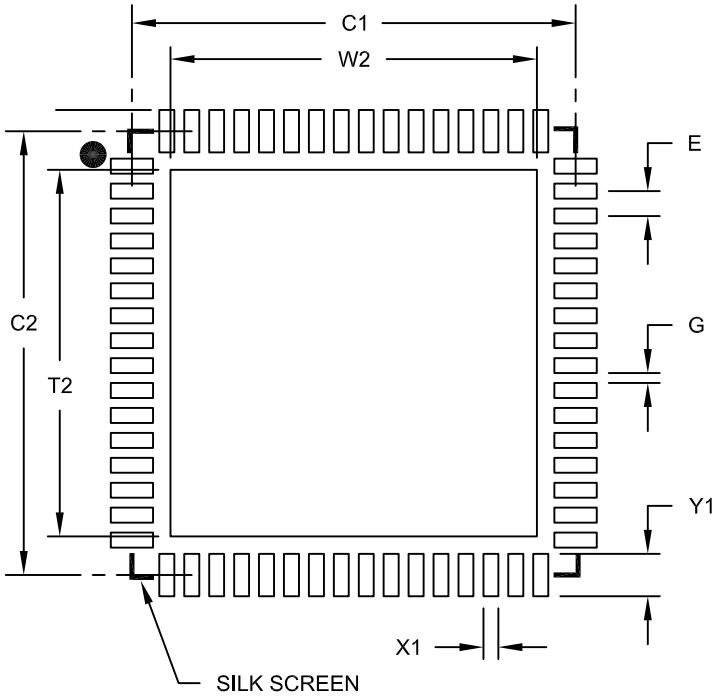
TABLE 29-40: OTG ELECTRICAL SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
USB313	VUSB	USB Voltage	3.0	—	3.6	V	Voltage on VUSB must be in this range for proper USB operation.
USB315	VILUSB	Input Low Voltage for USB Buffer	—	—	0.8	V	—
USB316	VIHUSB	Input High Voltage for USB Buffer	2.0	—	—	V	—
USB318	VDIFS	Differential Input Sensitivity	—	—	0.2	V	The difference between D+ and D- must exceed this value while VCM is met.
USB319	VCM	Differential Common Mode Range	0.8	—	2.5	V	—
USB320	ZOUT	Driver Output Impedance	28.0	—	44.0	Ω	—
USB321	VOL	Voltage Output Low	0.0	—	0.3	V	1.5 kΩ load connected to 3.6V.
USB322	VOH	Voltage Output High	2.8	—	3.6	V	1.5 kΩ load connected to ground.

Note 1: These parameters are characterized, but not tested in manufacturing.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	W2			7.35
Optional Center Pad Length	T2			7.35
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.85
Distance Between Pads	G	0.20		

Notes:

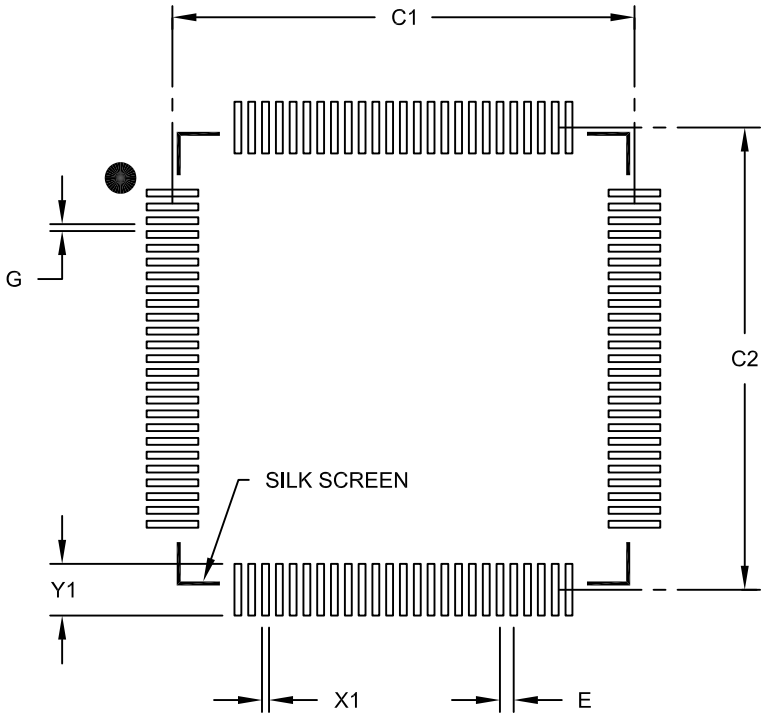
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2149A

100-Lead Plastic Thin Quad Flatpack (PT)-12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B

APPENDIX A: REVISION HISTORY

Revision E (July 2008)

- Updated the PIC32MX340F128H features in Table 1 to include 4 programmable DMA channels.

Revision F (June 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

Global changes include:

- Changed all instances of OSCI to OSC1 and OSCO to OSC2
- Changed all instances of VDDCORE and VDDCORE/VCAP to VCAP/VDDCORE
- Deleted registers in most sections, refer to the related section of the *"PIC32 Family Reference Manual"* (DS61132).

The other changes are referenced by their respective section in the following table.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, General Purpose and USB 32-bit Flash Microcontrollers"	Added a "Packages" column to Table 1 and Table 2. Corrected all pin diagrams to update the following pin names. • Changed PGC1/EMUC1 to PGEC1 • Changed PGD1/EMUD1 to PGED1 • Changed PGC2/EMUC2 to PGEC2 • Changed PGD2/EMUD2 to PGED2 Shaded appropriate pins in each diagram to indicate which pins are 5V tolerant. Added 64-Lead QFN package pin diagrams, one for General Purpose and one for USB.
Section 1.0 "Device Overview"	Reconstructed Figure 1-1 to include Timers, ADC and RTCC in the block diagram.
Section 2.0 "Guidelines for Getting Started with 32-bit Microcontrollers"	Added a new section to the data sheet that provides the following information: • Basic Connection Requirements • Capacitors • Master Clear Pin • ICSP™ Pins • External Oscillator Pins • Configuration of Analog and Digital Pins • Unused I/Os
Section 4.0 "Memory Organization"	Updated the memory maps, Figure 4-1 through Figure 4-6. All summary peripheral register maps were relocated to **Section 4.0 "Memory Organization"**.
Section 7.0 "Interrupt Controller"	Removed the "Address" column from Table 7-1.
Section 12.0 "I/O Ports"	Added a second paragraph in **Section 12.1.3 "Analog Inputs"** to clarify that all pins that share ANx functions are analog by default, because the AD1PCFG register has a default value of 0x0000.

TABLE A-3: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 29.0 "Electrical Characteristics"	Added the new V-Temp temperature range (-40ºC to +105ºC) to the heading of all specification tables. Updated the Ambient temperature under bias, updated the Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V, and added Voltage on VBUS with respect to Vss in Absolute Maximum Ratings. Added the characteristic, DC5a to Operating MIPS vs. Voltage (see Table 29-1). Updated or added the following parameters to the Operating Current (IDD) DC Characteristics: DC20, DC23, DC24c, DC25d, DC26c (see Table 29-5). Added the following parameters to the Idle Current (IIDLE) DC Characteristics: DC30c, DC31c, DC32c, DS33c, DC34c, DC35c, and DC36c (see Table 29-6). Added the following parameters to the Power-down Current (IPD) DC Characteristics: DC40g, DC40h, DC40i, DC41g, DC41h, DC42g, DC42h, DC42i, DC43h, and DC43i (see Table 29-7). Added the Brown-out Reset (BOR) Electrical Characteristics (see Table 29-10). Removed all Conditions from the Program Memory DC Characteristics (see Table 29-11). Removed the AC Characteristics voltage reference table (Table 29-15). Added Note 2 to the PLL Clock Timing Specifications (see Table 29-18). Updated the OC/PWM Module Timing Characteristics (see Figure 29-9). Added parameter IM51 and Note 3 to the I2Cx Bus Data Timing Requirements (Master Mode) (see Table 29-32). Added parameter numbers (AD13, AD14, and AD15) to the ADC Module Specifications (see Table 29-34). Updated the 10-bit ADC Conversion Rate Parameters (see Table 29-35). Updated parameter AD57 (TSAMP) in the Analog-to-Digital Conversion Timing Requirements (see Table 29-36). Updated the Conditions for parameters USB313, USB318, and USB319 in the OTG Electrical Specifications (see Table 29-40).
Section 30.0 "Packaging Information"	Updated the 64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] packing diagram.
Product Identification System	Added the new V-Temp (V) temperature information.